

Title (en)
Method for manufacturing a honeycomb structured body

Title (de)
Verfahren zur Herstellung eines Körpers mit Wabenstruktur

Title (fr)
Procédé de fabrication d'un élément structuré en nid d'abeille

Publication
EP 1847518 B2 20170531 (EN)

Application
EP 07003758 A 20070223

Priority
JP 2006308238 W 20060419

Abstract (en)
[origin: EP1847518A1] It is an object of the present invention to provide a method for manufacturing a honeycomb molded body that has the either one of the end portions of each of the cells assuredly sealed with a plug material layer of a desired shape. The method for manufacturing a honeycomb structured body of the present invention is configured to manufacture a honeycomb structured body comprising a honeycomb fired body manufactured by molding ceramic raw material to form a pillar-shaped honeycomb molded body having a multiplicity of cells disposed in parallel with one another in the longitudinal direction with a cell wall therebetween, and filling in either one of the end portions of the cells with a plug material paste, and firing this honeycomb molded body, wherein, after having filled in either one of the end portions of each of the cells of the honeycomb molded body with the plug material paste, a plug material paste drying process configured to dry the plug material paste by blowing hot air to the end faces of the honeycomb molded body is conducted.

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C04B 38/00 (2006.01)

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Citation (opposition)
Opponent :
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